



GE Energy

## Functional Testing Specification

*Parts & Repair Services  
Louisville, KY*

**LOU-GED-DS200TBQEG1BA**

### Test Procedure for a DS200TBQEG1 terminal board

**DOCUMENT REVISION STATUS:** Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	James Archibald	02/02/2015
B			
C			

© COPYRIGHT GENERAL ELECTRIC COMPANY

Hard copies are uncontrolled and are for reference only.

PROPRIETARY INFORMATION – THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION OF GENERAL ELECTRIC COMPANY AND MAY NOT BE USED OR DISCLOSED TO OTHERS, EXCEPT WITH THE WRITTEN PERMISSION OF GENERAL ELECTRIC COMPANY.

<b>PREPARED BY</b> J Archibald	<b>REVIEWED BY</b>	<b>REVIEWED BY</b>	<b>QUALITY APPROVAL</b> L. Groves
<b>DATE</b> 02/02/2015	<b>DATE</b>	<b>DATE</b>	<b>DATE</b> 2/2/2015

LOU-GED-DS200TBQBG1A REV. B	g  <b>GE Energy</b> Parts & Repair Services Louisville, KY	Page 2 of 3
--------------------------------	--	-------------

## 1. SCOPE

1.1 This is a functional testing procedure for a Card.

## 2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

## 3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein.  
Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

## 4. ENGINEERING REQUIREMENTS

### 4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

### 4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

## 5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)
1		30VDC Power or higher

<p>LOU-GED-DS200TBQBG1A REV. B</p>	<p><b>g</b></p> <p><b>GE Energy</b> Parts &amp; Repair Services Louisville, KY</p>	<p>Page 3 of 3</p>
--	--	--------------------

## 6. TESTING PROCESS

### 6.1 Testing Procedure

- 6.1.1 Apply +25Vdc to pin 1 of JLLR and – side of capacitor C1.
- 6.1.2 Verify +24Vdc +/- 5% at TBA pin 1 and 4.
- 6.1.3 Repeat step 6.1.1 and 6.1.2 for JLLS pin 1 and JLLT pin 1
- 6.1.4 Apply -25 volts to JQQR pin 29 and com to + side of C2.
- 6.1.5 Verify – 24 volt at TBA pin 21 and com to + side of C2
- 6.1.6 Repeat for step 6.1.4 and 6.1.5 for JQQS pin 29 and JQQT pin 29
- 6.1.7 Use LOU-GE-COMPTEST to test the remainder of the card.

### 6.2 Burning in card

- 6.2.1 connect +27vdc to to pin 1 of JLLS and com to – side of C1.
- 6.2.2 Connect a 470 ohm, 2w resistor from common to TBA pin 1 and 4.
- 6.2.3 Connect – 27 volts to JQQS pin 29 and com to the + side of C2
- 6.2.4 Connect a 470 ohm, 2w resistor from TBA pin 27 to TBA pin 21..
- 6.2.5 Normal repairs; Burn card in for 1 hours and verify +24vdc +/- 1vdc at each of the TB1 connections.
- 6.2.6 **All Revitalization Cards shall be burned-in for three (3) hours, check text box in SAP to determine if they fall into this category.**

### 6.3 \*\*\*TEST COMPLETE \*\*\*

## 7. NOTES

- 7.1 None at this time.

## 8. ATTACHMENTS

- 8.1 None at this time.